

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSL302SN H6327	**Issued**	24. June 2021
MA#	MA001190006		
Package	PG-TSOP6-6-6	**Weight***	13.65 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.010	0.07		723	
	noble metal	gold	7440-57-5	0.038	0.28		2803	
	inorganic material	silicon	7440-21-3	0.583	4.28	4.63	42760	46286
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		87	
	non noble metal	titanium	7440-32-6	0.006	0.04		433	
	non noble metal	chromium	7440-47-3	0.018	0.13		1299	
	non noble metal	copper	7440-50-8	5.882	43.11	43.29	431067	432886
wire	non noble metal	copper	7440-50-8	0.066	0.48	0.48	4811	4811
encapsulation	organic material	carbon black	1333-86-4	0.066	0.48		4812	
	plastics	epoxy resin	-	1.412	10.35		103456	
	inorganic material	silicondioxide	60676-86-0	5.089	37.29	48.12	372924	481192
leadfinish	non noble metal	tin	7440-31-5	0.299	2.19	2.19	21905	21905
plating	noble metal	silver	7440-22-4	0.176	1.29	1.29	12920	12920
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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